



## General Description

The HSU0020A is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

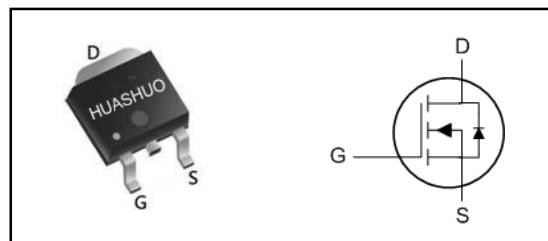
The HSU0020A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

V <sub>DS</sub>	100	V
R <sub>DS(ON),max</sub>	13	mΩ
I <sub>D</sub>	56	A

## TO252 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	56	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	36	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	120	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	143.6	mJ
I <sub>AS</sub>	Avalanche Current	53.6	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	83	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	1.5	°C/W



**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.09	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=30\text{A}$	---	---	13	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	2.0	---	4.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=30\text{A}$	---	58	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	---	3.0	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=30\text{A}$	---	48.5	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	13.7	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	18.9	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=30\text{A}$	---	22	---	ns
$T_r$	Rise Time		---	30	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	40	---	
$T_f$	Fall Time		---	12	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2947	---	pF
$C_{\text{oss}}$	Output Capacitance		---	390	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	177	---	

**Diode Characteristics**

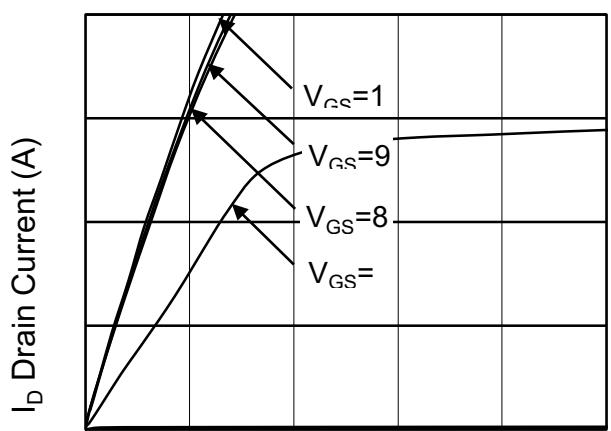
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	56	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	120	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_S=A$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=30\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	29.5	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	35	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=53.6\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

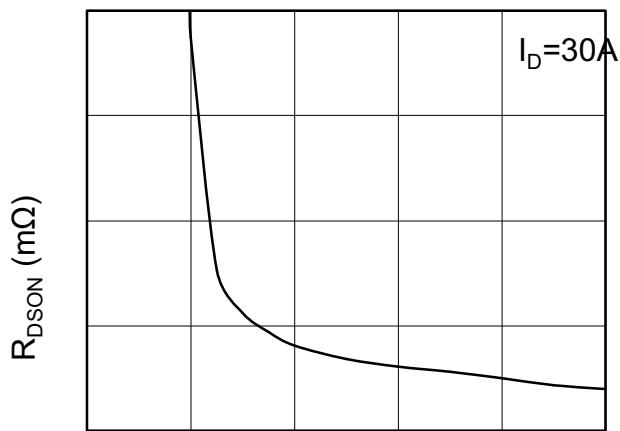


### Typical Characteristics



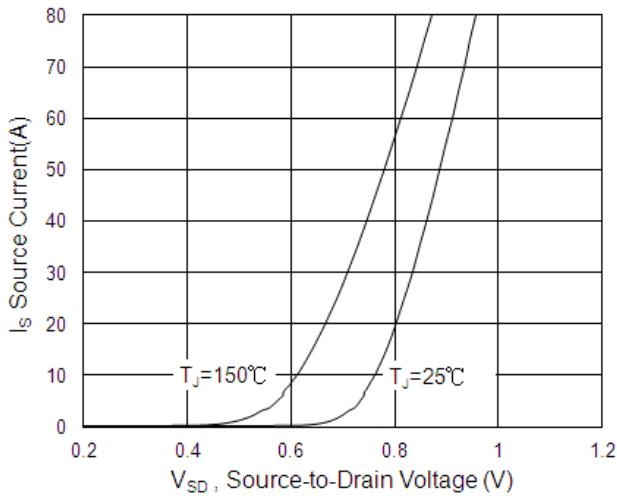
$V_{DS}$ , Drain-to-Source Voltage (V)

Fig.1 Typical Output Characteristics



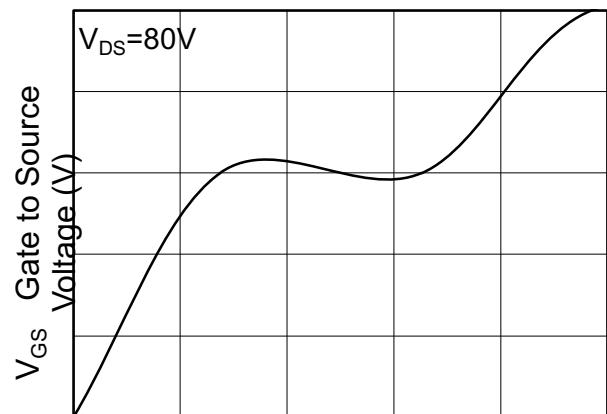
$V_{GS}$  (V)

Fig.2 On-Resistance v.s Gate-Source



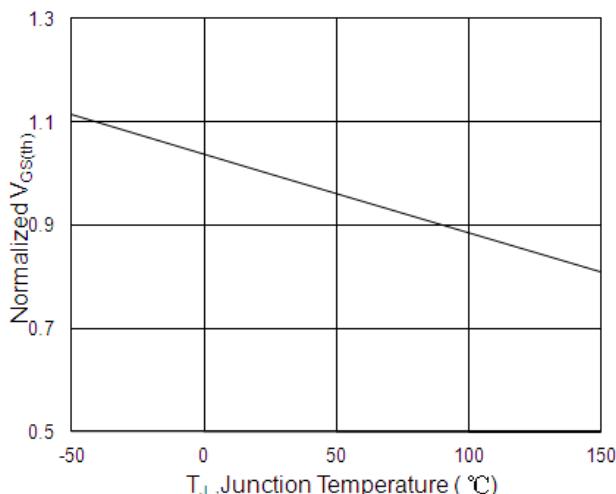
$V_{SD}$ , Source-to-Drain Voltage (V)

Fig.3 Forward Characteristics of Reverse



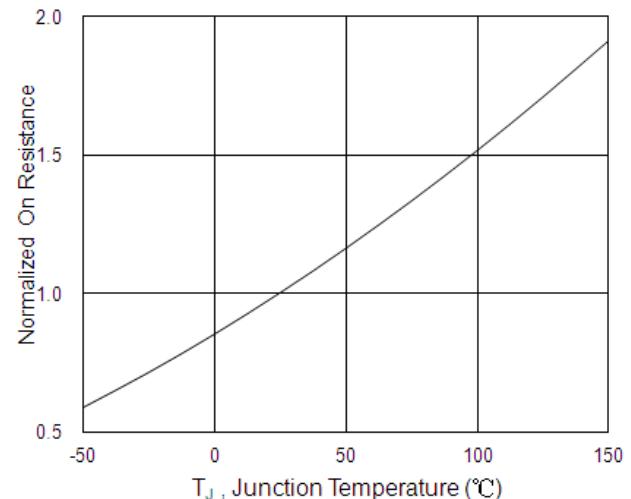
$Q_G$ , Total Gate Charge (nC)

Fig.4 Gate-Charge Characteristics



$T_J$ , Junction Temperature (°C)

Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$



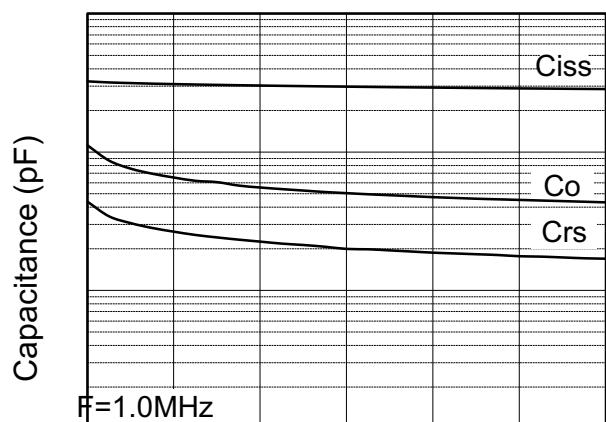
$T_J$ , Junction Temperature (°C)

Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$

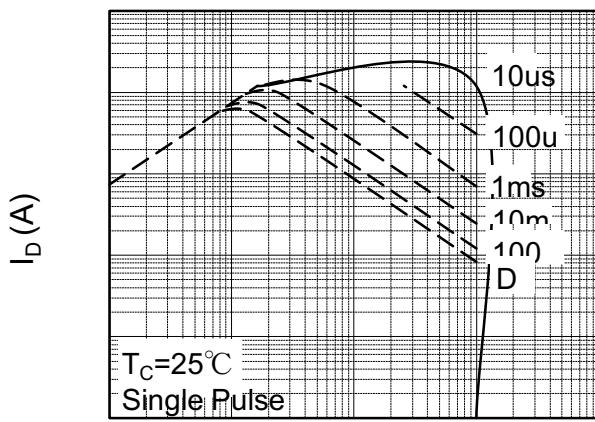


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HSU0020A



$V_{DS}$ , Drain to Source Voltage(V)



$V_{DS}$  (V)

Fig.7 Capacitance

Fig.8 Safe Operating Area

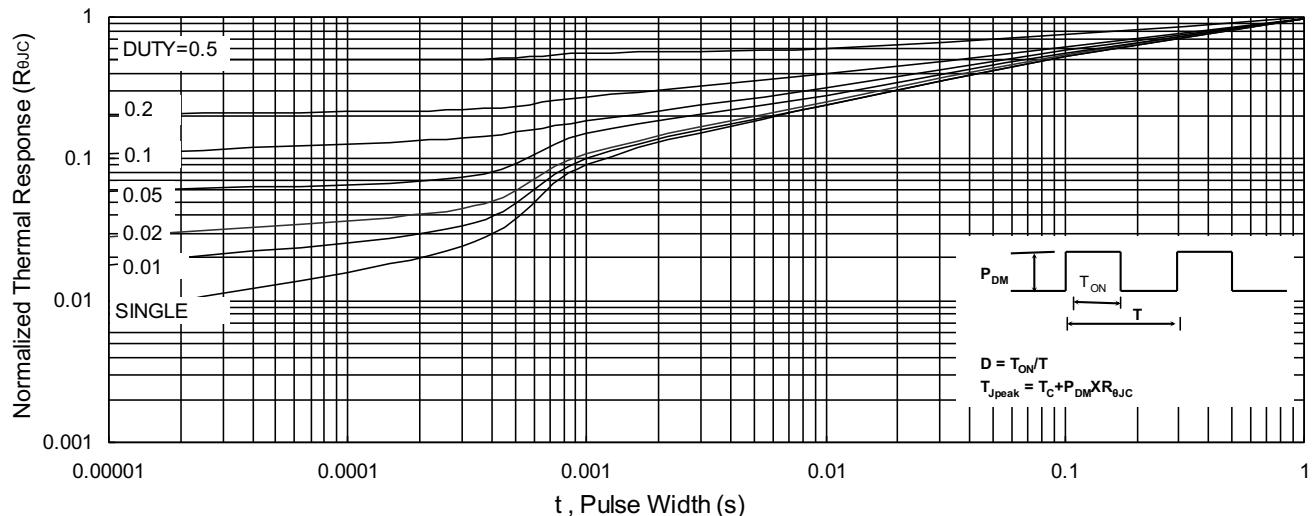


Fig.9 Normalized Maximum Transient Thermal Impedance

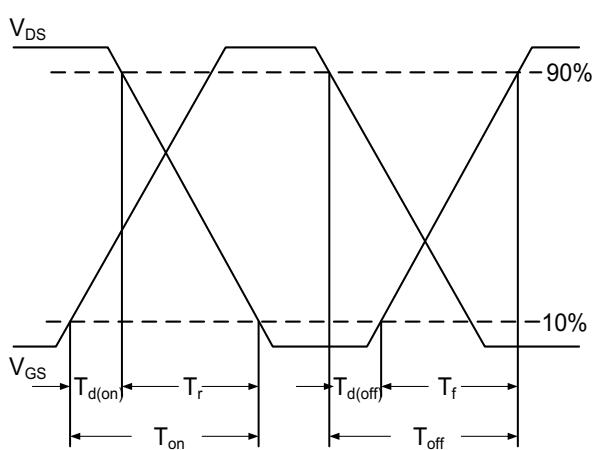


Fig.10 Switching Time Waveform

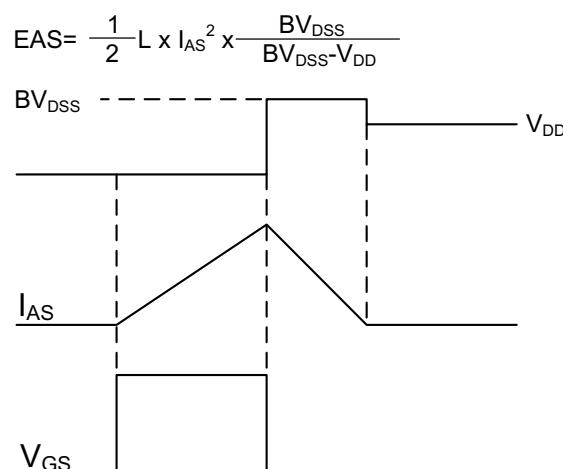


Fig.11 Unclamped Inductive Switching